



## Material Content Data Sheet



<b>Sales Product Name</b>	BSB044N08NN3 G			<b>Issued</b>	31. January 2019			
<b>MA#</b>	MA001355338							
<b>Package</b>	MG-WDSO-N-2-5			<b>Weight*</b>	86.37 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.356	7.36	7.36	73594	73594
leadframe	non noble metal	copper	7440-50-8	74.415	86.17	86.17	861570	861570
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.24		2445	
	noble metal	silver	7440-22-4	0.840	0.97	1.21	9725	12170
plating	non noble metal	nickel	7440-02-0	0.211	0.24	0.24	2445	2445
solder	non noble metal	copper	7440-50-8	0.011	0.01		127	
	noble metal	silver	7440-22-4	0.066	0.08		763	
	non noble metal	tin	7440-31-5	2.119	2.45	2.54	24528	25418
glue	plastics	epoxy resin	-	0.254	0.29		2942	
	noble metal	silver	7440-22-4	1.561	1.81	2.10	18071	21013
passivation	plastics	epoxy resin	-	0.327	0.38	0.38	3790	3790
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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